21503-□□□□U 80 □□□□□□ □□□□□ □□□ □□□□□□ □□□□□□□ □□□□ □□□□

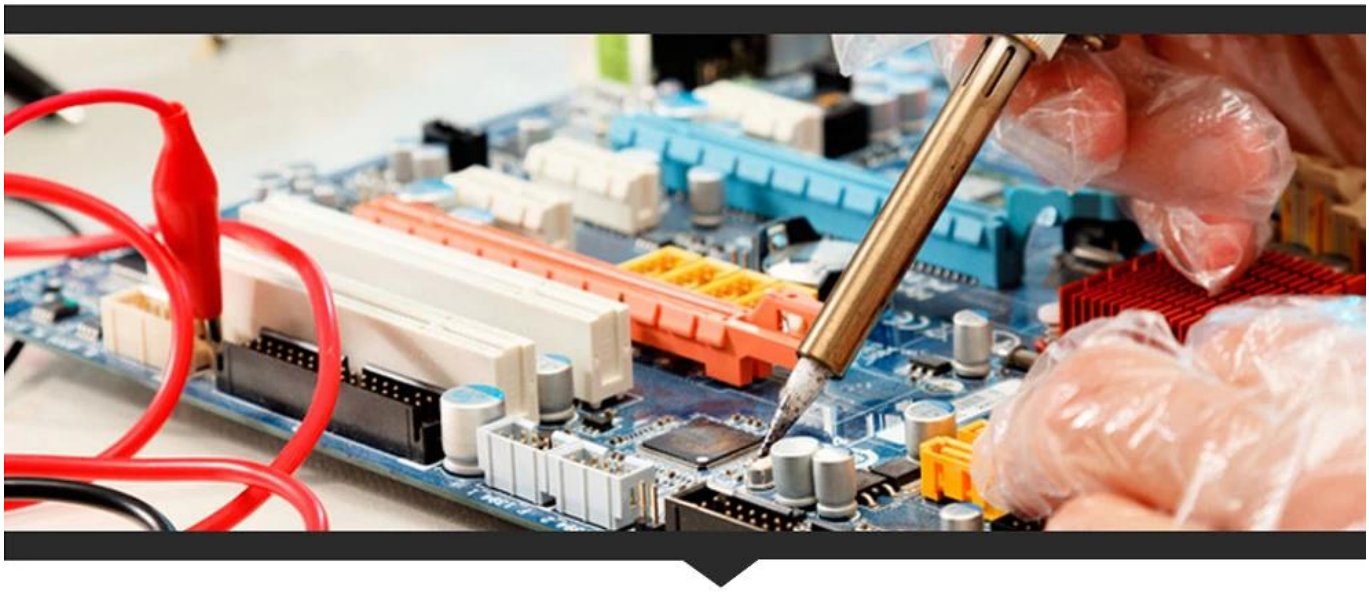
:□□□□□□□□

□□□□□: BST-21503U
80 :□□□G
45 * 80 :□□□□mm □
60 :□□□□□□ □□□□□□ ℃

PRODUCT DISPLAY

PRODUCT DETAILS

Name: Soldering Paste	Model: BST-21503U
Size: Φ80*45mm	Weight: 80g
Composition: Solder powder, resin	Melting point:60°C



- Stable performance,Not volatile, long life cycle, the amount of province;
- Non-toxic non-irritating odor, the use of safe and reliable;
- The IC and PCB are not corrosive
- Its boiling point is only slightly higher than the melting point of solder.

Features: Solder melting at the time of soldering begins to boil endothermic vaporization, which can be maintained at this temperature using IC and PCB temperatures. In the demolition of the chip with a lot of solder paste, it melts fast, you can flow to the BGA chip below. Rosin is solid without solder paste convenient.

PRODUCT PHOTOGRAPH

BEST
SOLDERING PASTE
21503U
MADE IN CHINA
BEST
SOLDERING PASTE
21503U
MADE IN CHINA